Low-Voltage CMOS Octal Buffer

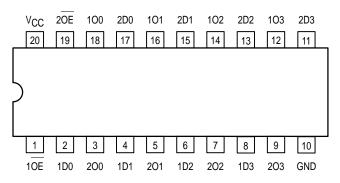
With 5V-Tolerant Inputs and Outputs (3-State, Non-Inverting)

The MC74LCX244 is a high performance, non-inverting octal buffer operating from a 2.7 to 3.6V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A VI specification of 5.5V allows MC74LCX244 inputs to be safely driven from 5V devices. The MC74LCX244 is suitable for memory address driving and all TTL level bus oriented transceiver applications.

Current drive capability is 24mA at the outputs. The Output Enable (OE) input, when HIGH, disables the output by placing them in a HIGH Z condition.

- Designed for 2.7 to 3.6V V_{CC} Operation
- 5V Tolerant Interface Capability With 5V TTL Logic
- · Supports Live Insertion and Withdrawal
- IOFF Specification Guarantees High Impedance When VCC = 0V
- LVTTL Compatible
- LVCMOS Compatible
- · 24mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current in All Three Logic States (10μA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500mA
- ESD Performance: Human Body Model >2000V; Machine Model >200V

Pinout: 20-Lead (Top View)



MC74LCX244



LOW-VOLTAGE CMOS OCTAL BUFFER



DW SUFFIX

PLASTIC SOIC CASE 751D-04



M SUFFIX

PLASTIC SOIC EIAJ CASE 967-01



SD SUFFIX

PLASTIC SSOP CASE 940C-03



DT SUFFIX PLASTIC TSSOP CASE 948E-02

PIN NAMES

REV 3

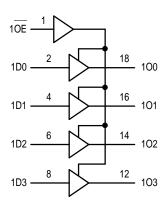
Pins	Function
nOE	Output Enable Inputs
1Dn, 2Dn	Data Inputs
1On, 2On	3–State Outputs

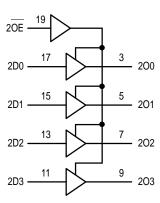


9/95

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LOGIC DIAGRAM





INPUTS		OUTPUTS
10E 20E	1Dn 2Dn	10n, 20n
L	L	L
L	Н	Н
Н	Х	Z

H = High Voltage Level; L = Low Voltage Level; Z = High Impedance State; X = High or Low Voltage Level and Transitions Are Acceptable, for I_{CC} reasons, DO NOT FLOAT Inputs

ABSOLUTE MAXIMUM RATINGS*

Symbol	Parameter	Value	Condition	Unit
VCC	DC Supply Voltage	-0.5 to +7.0		V
VI	DC Input Voltage	$-0.5 \le V_1 \le +7.0$		V
VO	DC Output Voltage	$-0.5 \le V_{O} \le +7.0$	Output in 3–State	V
		$-0.5 \le V_{O} \le V_{CC} + 0.5$	Note 1.	V
Ιικ	DC Input Diode Current	– 50	V _I < GND	mA
lok	DC Output Diode Current	-50	V _O < GND	mA
		+50	AO > ACC	mA
Io	DC Output Source/Sink Current	±50		mA
Icc	DC Supply Current Per Supply Pin	±100		mA
IGND	DC Ground Current Per Ground Pin	±100		mA
TSTG	Storage Temperature Range	-65 to +150		°C

^{*} Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute–maximum–rated conditions is not implied.

1. Output in HIGH or LOW State. I_O absolute maximum rating must be observed.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Тур	Max	Unit
Vcc	Supply Voltage Operating Data Retention Only	2.0 1.5	3.3 3.3	3.6 3.6	V
VI	Input Voltage	0		5.5	V
Vo	Output Voltage (HIGH or LOW State) (3–State)	0 0		VCC 5.5	V
loн	HIGH Level Output Current, V _{CC} = 3.0V – 3.6V			-24	mA
loL	LOW Level Output Current, V _{CC} = 3.0V – 3.6V			24	mA
^I ОН	HIGH Level Output Current, V _{CC} = 2.7V – 3.0V			-12	mA
loL	LOW Level Output Current, V _{CC} = 2.7V – 3.0V			12	mA
TA	Operating Free–Air Temperature	-40		+85	°C
Δt/ΔV	Input Transition Rise or Fall Rate, V_{IN} from 0.8V to 2.0V, $V_{CC} = 3.0V$	0		10	ns/V

DC ELECTRICAL CHARACTERISTICS

			$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		
Symbol	Characteristic	Condition	Min	Max	Unit
V _{IH}	HIGH Level Input Voltage (Note 2.)	$2.7V \le V_{CC} \le 3.6V$	2.0		V
V _{IL}	LOW Level Input Voltage (Note 2.)	$2.7V \le V_{CC} \le 3.6V$		0.8	V
Vон	HIGH Level Output Voltage	$2.7V \le V_{CC} \le 3.6V; I_{OH} = -100\mu A$	V _{CC} – 0.2		V
		$V_{CC} = 2.7V; I_{OH} = -12mA$	2.2		
		$V_{CC} = 3.0V; I_{OH} = -18mA$	2.4		
		$V_{CC} = 3.0V; I_{OH} = -24mA$	2.2		
VOL	LOW Level Output Voltage	$2.7V \le V_{CC} \le 3.6V$; $I_{OL} = 100\mu A$		0.2	V
		$V_{CC} = 2.7V; I_{OL} = 12mA$		0.4	
		V _{CC} = 3.0V; I _{OL} = 16mA		0.4	
		$V_{CC} = 3.0V; I_{OL} = 24mA$		0.55	

^{2.} These values of V_I are used to test DC electrical characteristics only.

DC ELECTRICAL CHARACTERISTICS (continued)

			$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		
Symbol	Characteristic	Condition	Min	Max	Unit
lį	Input Leakage Current	$2.7V \le V_{CC} \le 3.6V$; $0V \le V_{I} \le 5.5V$		±5.0	μΑ
loz	3–State Output Current	$2.7 \le V_{CC} \le 3.6V$; $0V \le V_O \le 5.5V$; $V_I = V_{IH}$ or V_{IL}		±5.0	μΑ
loff	Power-Off Leakage Current	$V_{CC} = 0V$; V_I or $V_O = 5.5V$		10	μΑ
ICC	Quiescent Supply Current	$2.7 \le V_{CC} \le 3.6V$; $V_I = GND \text{ or } V_{CC}$		10	μΑ
		$2.7 \le V_{CC} \le 3.6V$; $3.6 \le V_I$ or $V_O \le 5.5V$		±10	μΑ
∆ICC	Increase in I _{CC} per Input	$2.7 \le V_{CC} \le 3.6V; V_{IH} = V_{CC} - 0.6V$		500	μΑ

AC CHARACTERISTICS ($t_R = t_F = 2.5 ns$; $C_L = 50 pF$; $R_L = 500 \Omega$)

			Limits			
			T _A = -40°C to +85°C			
			V _{CC} = 3.0	V to 3.6V	V _{CC} = 2.7V	
Symbol	Parameter	Waveform	Min	Max	Max	Unit
^t PLH ^t PHL	Propagation Delay Input to Output	1	1.5 1.5	6.5 6.5	7.5 7.5	ns
^t PZH ^t PZL	Output Enable Time to High and Low Level	2	1.5 1.5	8.0 8.0	9.0 9.0	ns
^t PHZ ^t PLZ	Output Disable Time From High and Low Level	2	1.5 1.5	7.0 7.0	8.0 8.0	ns
^t OSHL ^t OSLH	Output-to-Output Skew (Note 3.)			1.0 1.0		ns

^{3.} Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH–to–LOW (toshl) or LOW–to–HIGH (tosl); parameter guaranteed by design.

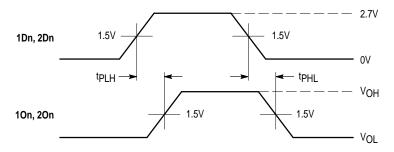
DYNAMIC SWITCHING CHARACTERISTICS

			T _A = +25°C			
Symbol	Characteristic	Condition	Min	Тур	Max	Unit
V _{OLP}	Dynamic LOW Peak Voltage (Note 4.)	$V_{CC} = 3.3V$, $C_L = 50pF$, $V_{IH} = 3.3V$, $V_{IL} = 0V$		0.8		V
VOLV	Dynamic LOW Valley Voltage (Note 4.)	$V_{CC} = 3.3V$, $C_L = 50pF$, $V_{IH} = 3.3V$, $V_{IL} = 0V$		0.8		V

^{4.} Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

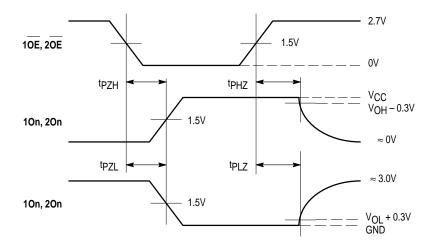
CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C _{IN}	Input Capacitance	$V_{CC} = 3.3V$, $V_I = 0V$ or V_{CC}	7	pF
C _{OUT}	Output Capacitance	$V_{CC} = 3.3V$, $V_I = 0V$ or V_{CC}	8	pF
C _{PD}	Power Dissipation Capacitance	10MHz, V_{CC} = 3.3V, V_I = 0V or V_{CC}	25	pF



WAVEFORM 1 - PROPAGATION DELAYS

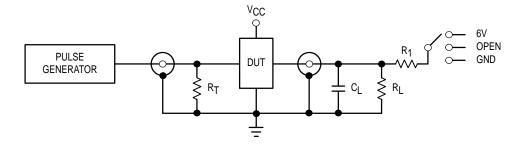
 t_R = t_F = 2.5ns, 10% to 90%; f = 1MHz; t_W = 500ns



WAVEFORM 2 - OUTPUT ENABLE AND DISABLE TIMES

 t_R = t_F = 2.5ns, 10% to 90%; f = 1MHz; t_W = 500ns

Figure 1. AC Waveforms



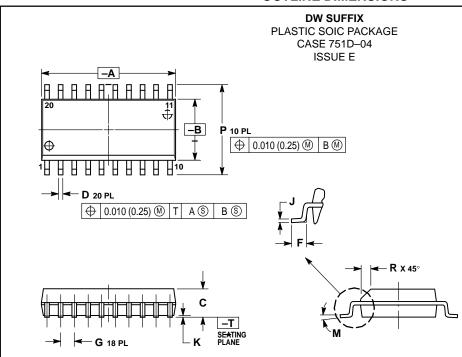
TEST	SWITCH
tPLH, tPHL	Open
tPZL, tPLZ	6V
Open Collector/Drain tpLH and tpHL	6V
^t PZH, ^t PHZ	GND

 C_L = 50pF or equivalent (Includes jig and probe capacitance) R_L = R_1 = 500 Ω or equivalent R_T = Z_{OUT} of pulse generator (typically 50 Ω)

Figure 2. Test Circuit

5

OUTLINE DIMENSIONS

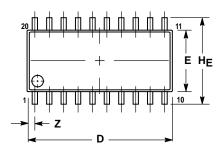


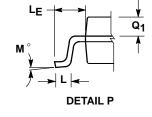
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
 - ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.150 (0.006) PER SIDE.
- 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

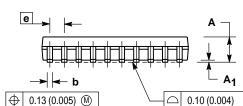
	MILLIMETERS		INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	12.65	12.95	0.499	0.510	
В	7.40	7.60	0.292	0.299	
С	2.35	2.65	0.093	0.104	
D	0.35	0.49	0.014	0.019	
F	0.50	0.90	0.020	0.035	
G	1.27	BSC	0.050 BSC		
J	0.25	0.32	0.010	0.012	
K	0.10	0.25	0.004	0.009	
M	0°	7°	0°	7°	
Р	10.05	10.55	0.395	0.415	
R	0.25	0.75	0.010	0.029	

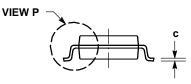
M SUFFIX

PLASTIC SOIC EIAJ PACKAGE CASE 967-01 ISSUE O









NOTES:

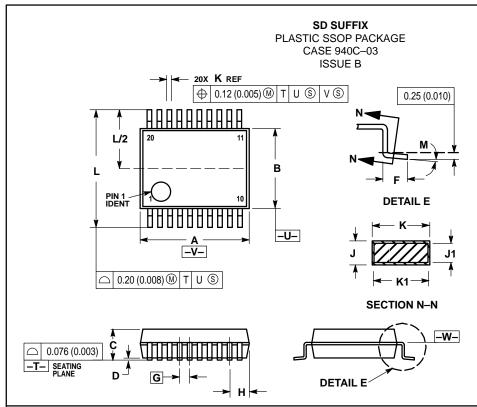
- 1 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- Y14.5M, 1982.

 2 CONTROLLING DIMENSION: MILLIMETER.

 3 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- PER SIDE.
 TERMINAL NUMBERS ARE SHOWN FOR
 REFERENCE ONLY.
 THE LEAD WIDTH DIMENSION (b) DOES NOT
 INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) DANIORAR FRO I RUSION SHALL BE 0.08 (0.003)
 TOTAL IN EXCESS OF THE LEAD WIDTH
 DIMENSION AT MAXIMUM MATERIAL CONDITION.
 DAMBAR CANNOT BE LOCATED ON THE LOWER
 RADIUS OR THE FOOT. MINIMUM SPACE
 BETWEEN PROTRUSIONS AND ADJACENT LEAD
 TO BE 0.46 (0.018).

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
С	0.18	0.27	0.007	0.011
D	12.35	12.80	0.486	0.504
E	5.10	5.45	0.201	0.215
е	1.27	BSC	0.050) BSC
ΗE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10°
Q_1	0.70	0.90	0.028	0.035
Z		0.81		0.032

OUTLINE DIMENSIONS



- NOTES:
 13 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 14 CONTROLLING DIMENSION: MILLIMETER.
- 14 CONTROCLING DIMENSION, MILLIUMETER.
 15 DIMENSION A DOES NOT INCLUDE MOLD FLASH,
 PROTRUSIONS OR GATE BURRS. MOLD FLASH
 OR GATE BURRS SHALL NOT EXCEED 0.15
- (0.006) PER SIDE.

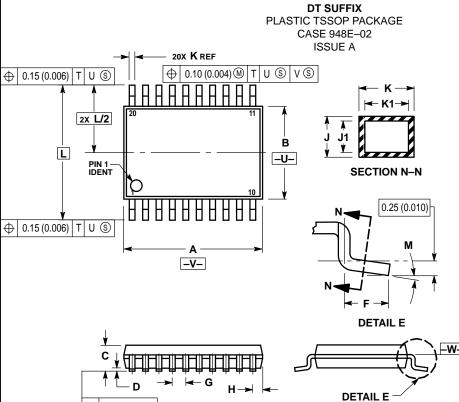
 16 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

 17 DIMENSION K DOES NOT INCLUDE DAMBAR
- PROTRUSION/INTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF K DIMENSION AT MAXIMUM MATERIAL CONDITION DAMBAR INTRUSION SHALL NOT REDUCE DIMENSION K BY MORE THAN 0.07 (0.002) AT LEAST MATERIAL
 CONDITION.

 18 TERMINAL NUMBERS ARE SHOWN FOR
 REFERENCE ONLY.

 19 DIMENSION A AND B ARE TO BE DETERMINED
 AT DATUM PLANE—W—.

	MILLIN	IETERS	INCHES			
DIM	MIN	MAX	MIN	MAX		
Α	7.07	7.33	0.278	0.288		
В	5.20	5.38	0.205	0.212		
С	1.73	1.99	0.068	0.078		
D	0.05	0.21	0.002	0.008		
F	0.63	0.95	0.024	0.037		
G	0.65 BSC		0.026 BSC			
Н	0.59	0.75	0.023	0.030		
۲	0.09	0.20	0.003	0.008		
J1	0.09	0.16	0.003	0.006		
K	0.25	0.38	0.010	0.015		
K1	0.25	0.33	0.010	0.013		
Ĺ	7.65	7.90	0.301	0.311		
М	0 °	8°	0 °	8 °		



0.100 (0.004) -T- SEATING PLANE

- 6 DIMENSIONING AND TOLERANCING PER ANSI
- 714.5M, 1982.
 7 CONTROLLING DIMENSION: MILLIMETER.
 8 DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- DIMENSION B DOES NOT INCLUDE INTERLEAD
 FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- 10 DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.

 11 TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.

 12 DIMENSION A AND B ARE TO BE DETERMINED
- AT DATUM PLANE -W-.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	6.40	6.60	0.252	0.260
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
Н	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

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